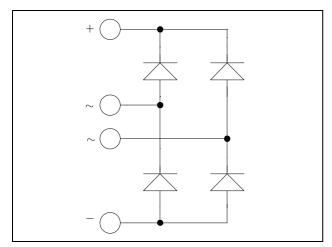


ISOTOP® Fast Diode Full Bridge Power Module

 $V_{RRM} = 1700V$ $I_F = 50A$ @ Tc = 80°C

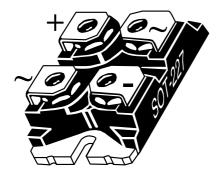


Application

- Switch mode power supplies rectifier
- Induction heating
- Welding equipment
- High speed rectifiers

Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
- High level of integration
- ISOTOP® Package (SOT-227)



Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter				Max ratings	Unit
V_R	Maximum DC reverse Voltage			1700	17	
V_{RRM}	Maximum Peak Repetitive Revers	e Voltage			1700	V
$I_{F(AV)}$	Maximum Average Forward Current	Duty cycle = 50%		$T_C = 80$ °C	50	A
I_{FRM}	Maximum repetitive forward curre by T _{Imax}	ent limited	8.3ms	$T_J = 45$ °C	100	11

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com



All ratings @ $T_j = 25$ °C unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V_{F}	Diode Forward Voltage	$I_F = 50A$	$T_i = 25^{\circ}C$		1.8	2.2	V
			$T_{j} = 125^{\circ}C$		1.9		
I_{RM}	Maximum Reverse Leakage Current	$V_{R} = 1700V$	$T_i = 25^{\circ}C$	250	250	^	
		V _R - 1700 V	$T_j = 125$ °C			500	μΑ

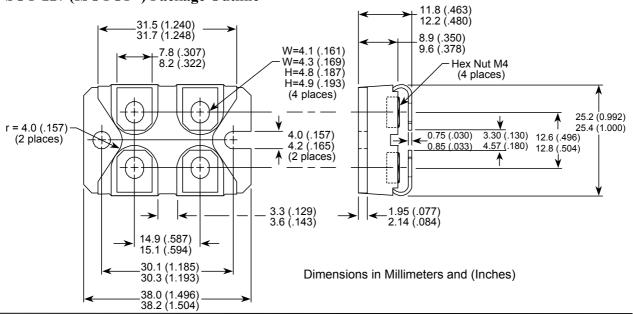
Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
t _{rr}	Reverse Recovery Time		$T_j = 25^{\circ}C$		385		- ns
		$I_F = 50A$ $V_R = 900V$ $di/dt = 800A/\mu s$	$T_{i} = 125^{\circ}C$		420		
Q _{rr}	Reverse Recovery Charge		$T_j = 25^{\circ}C$		14		μ C
			$T_j = 125$ °C		23		
E _{rr}	Reverse Recovery Energy		$T_j = 25^{\circ}C$		6		mJ
			$T_j = 125$ °C		12		1113

Thermal and package characteristics

Symbol	Characteristic	Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal resistance			0.7	°C/W
R_{thJA}	Junction to Ambient			20	C/ VV
V_{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz	2500			V
T_{J}, T_{STG}	Storage Temperature Range	-55		150	°C
$T_{ m L}$	Max Lead Temp for Soldering:0.063" from case for 10 sec			300	
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)			1.5	N.m
Wt	Package Weight		29.2		g

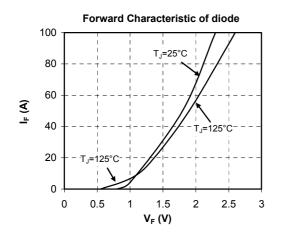
SOT-227 (ISOTOP®) Package Outline

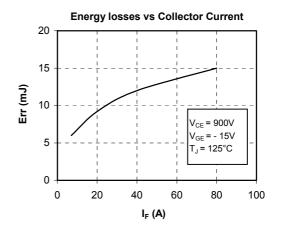


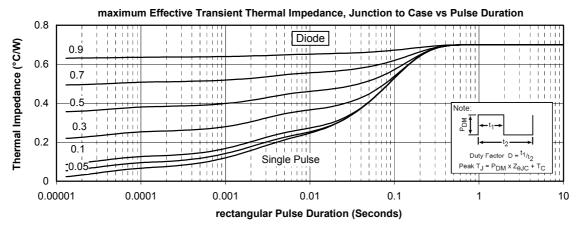
APT50DF170HJ-Rev 1 October 2012



Typical Performance Curve







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